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2. Analog and Mixed-Signal ICs

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3. Digital ICs

Co-Chair:

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Lin Jun, *Nan Jing University, China*

LI LIN, *Hisilicon, China*

Shan Weiwei, *Southeast University, China*

Zhang Duoli, *Hefei U Tech, China*

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Li Dan, *XJTU, China*

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5. Modeling, CAD and Testing

Co-Chair:

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6. Device and Process Technologies

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7. Packaging and Hybrid Integration

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